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Application ID: 10626150 
Title of Invention: PLASTIC INTEGRATED CIRCUIT
PACKAGE AND METHOD AND
LEADFRAME FOR MAKING THE
PACKAGE
First Named Inventor: THOMAS GLENN
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Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE	
<p>Application Number: 10/626150 Date: 2003-07-24 First Named Applicant: THOMAS P.</p> <p>Confirmation Number: 9302 Attorney Docket Number: AMKOR007C2</p>		
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Submitted by:	Elec. Sign.	Sign. Capacity
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids4-usidst.xml us-ids.dtd us-ids.xsl	
Comments		



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND AND LEADFRAME FOR MAKING THE PACKAGE									
Application Number:	10/626150									
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First Named Applicant:	THOMAS GLENN									
Attorney Docket Number:	AMKOR007C2									
Art Unit:	2815									
Search string:	(5886398 or 5894108 or 5897339 or 5900676 or 5903049 or 5903050 or 5909053 or 5915998 or 5917242 or 5939779 or 5942794 or 5951305 or 5959356 or 5969426 or 5973388 or 5976912 or 5977613 or 5977615 or 5977630 or 5981314 or 5986333 or 5986885 or 6001671 or 6013947 or 6018189 or 6020625 or 6025640 or 6031279 or 6034423 or RE36613 or 6040626 or 6043430 or 6060768 or 6060769 or 6072228 or 6075284 or 6081029 or 6084310 or 6087715 or 6087722 or 6100594 or 6114752 or 6113474 or 6118174 or 6118184 or 6130115 or 6130473 or RE36907 or 6133623 or 6140154).pn.									
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents										
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass			
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Signature

Examiner Name	Date